EVALUATE CMP FOR CONDUCTIVE LAYER THICKNESS
LEI 1500 FAMILY FOR NON-CONTACT, NON-DESTRUCTIVE HIGH THROUGHPUT MAPPING AND UNIFORMITY COPPER AND BARRIER LAYERS

LEI'S 1500 Family provides effective characterization of your CMP Process performance for conductive layers such as copper and copper barrier layers. With our Non-Contact, Non-Destructive 1500 systems you can optimize CMP processing and perform process control to keep operations on target and within budget. Mapping of layer thickness values determines film uniformity based on material resistivity. Significant limitations of 4 point probes are avoided.

Comparison of:

LEI Non-Contact-Non Destructive	VS	Four Point Probe
No Probe Qualification		Probe Qualification Required
No Probe damage or replacement		Probe damage is progressive may be rapid and requires replacement
Not affected by native surface oxides		Probe may not penetrate native oxide may be caused by probe contamination
No thin film damage with repeated measurement		Each probe cycle causes progressive thin film damage
No cross contamination		Probing different materials or contaminated materials can transfer the materials or contamination
Measurement precision consistently better than best qualified four point probe results.		Acceptable precision requires probe qualification and monitoring

For more information, Contact:

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